							F	REVISI	ONS										
LTR					DESCR	IPTION	١					DA	DATE (YR-MO-DA)				APPROVED		
Α	Technical c	Technical changes in table I. Changes to figure 1 dimension changes throughout.					ension	ns. Editorial 93-08-25				M. A. FRYE							
В	Changes in	Changes in accordance with N.O.R. 5962-R063-94.										94-0)7-15		M. A. FRYE				
С	Drawing up	dated to	reflect	curren	nt requi	rement	s ro	ı					00-0)8-29		R. MONNIN			
THE ORIGINA	L FIRST SHEE	ET OF TH	IS DR.	AWING	G HAS	BEEN	REPL <i>A</i>	ACED.											
	IL FIRST SHEE	ET OF TH	IS DR.	AWING	G HAS	BEEN	REPLA	ACED.											
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REV	IL FIRST SHEE	ET OF TH	IS DR.	AWING	G HAS	BEEN	REPLA	ACED.											
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REV SHEET REV SHEET REV STATUS		ET OF TH			G HAS				C 4	C 5	C 6	C 7	C 8	C 9	C 10	C 11	C 12		
REV SHEET REV SHEET REV STATUS OF SHEETS MIC N/A	NDARD		REV SHEE PREP RICK	ET PARED K C. OI	BY	C 1	С	С		5	6 EFEN	7 SE SI	8 UPPL	9 .Y CE	10	11 COL	12 .UMBI	JS	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DR. THIS DRAWI FOR U DEPA AND AGE	INDARD	BLE	REV SHEE PREP RICK CHA	ET PARED EXC. OF	BY FFICER BY E. BES	C 1 R GORE	C 2	С	MIC REC	DI DI	6 EFEN CIRCU	SE SI COL	UPPL UMBI	9 .Y CE US, O	NTER	11 COL 43216	12 .UMBI	JS	

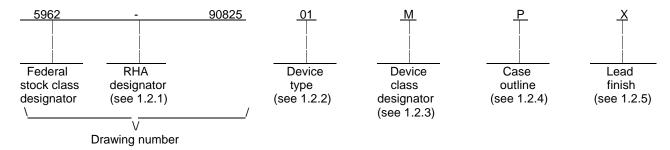
SHEET

1 OF

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1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.
 - 1.2 PIN. The PIN is as shown in the following example:



- 1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	LT1070	High power switching regulator with internal 5 A switch
02	LT1071	High power switching regulator with internal 2.5 A switch
03	LT1072	High power switching regulator with internal 1.25 A switch
04	LT1070HV	High power switching regulator with internal 5 A switch
05	LT1071HV	High power switching regulator with internal 2.5 A switch
06	LT1072HV	High power switching regulator with internal 1.25 A switch

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as follows:

Device class	<u>Device requirements documentation</u>
М	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Р	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
Υ	See figure 1	4	Flange mount, similar to TO-3

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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1.3 Absolute maximum ratings. 1/

Supply voltage (V_{IN}):

Device types 04, 05, and 0660 V

Switch output voltage (V_{SW}):

Junction temperature (T_J)+150°C

Storage temperature range-65°C to +150°C

Lead temperature (soldering, 10 seconds)+300°C

Thermal resistance, junction-to-case (θ_{JC}):

Case PSee MIL-STD-1835

Case Y:

Device types 03 and 068°C/W

Thermal resistance, junction-to-ambient (θ_{JA}):

1.4 Recommended operating conditions.

Ambient operating temperature range (T_A)-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-973 - Configuration Management.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

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HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics and post irradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and post irradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

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TABLE I. <u>Electrical performance characteristics</u>.

Test	0 1 1	Conditions $\underline{1}$ / -55°C \leq T _A \leq +125°C	Group A	Device	l ir	mits	Unit
Test	Symbol	unless otherwise specified	subgroups	type		ilito	Offic
					Min	Max	
Error amplifier clamp voltage		High clamp, V _{FB} = 1 V,	1	All	1.8	2.3	V
voitage		T _A = +25°C					
		Low clamp, V _{FB} = 1.5 V,			0.25	0.52	
		T _A = +25°C					
Error amplifier voltage	A _V	0.9 V ≤ V _C pin ≤ 1.4 V,	1	All	500		V/V
gain		T _A = +25°C					
Supply current	IQ	$3 \text{ V} \leq \text{V}_{IN} \leq \text{V}_{MAX}$	1	All		9	mA
		V _C pin = 0.6 V,					
		T _A = +25°C					
Normal/flyback threshold on feedback pin		T _A = +25°C	1	All	0.4	0.54	V
Flyback reference	V _{FB}	I _{FB} = 50 μA	1	All	15	17.6	V
voltage	'5	15	2,3	-	14	18	
Change in flyback reference voltage	ΔV_{FB}	50 μ A \leq I _{FB} \leq 1 mA,	1	All	4.5	8.5	V
		T _A = +25°C					
Flyback reference voltage line regulation	ΔV_{FB} /	$I_{FB} = 50 \ \mu A, \ \underline{2}/$	1	All		0.03	%/V
vollage into regulation	ΔV_{IN}	$3 \text{ V} \leq \text{V}_{IN} \leq \text{V}_{MAX}$					
		T _A = +25°C					
Flyback amplifier transconductance (gm)		$\Delta I_C = \pm 10 \mu A$,	1	All	150	500	μmho
transconductance (gm)		T _A = +25°C					
Flyback amplifier source and sink current		Source, V _C pin = 0.6 V,	1,2,3	All	15	70	μА
and sink current		I _{FB} = 50 μA					
		Sink, V _C pin = 0.6 V,			25	70	
		I _{FB} = 50 μA					
Supply current increase	Δl _{IN} /	T _A = +25°C	1	All		35	mA/A
during switch on-time	ΔISW						
Maximum switch duty	DC	T _A = +25°C	1	All	90	97	%
cycle 	(max)						

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Lir	mits	Unit
					Min	Max	
Shutdown mode supply		$3 \text{ V} \leq \text{V}_{IN} \leq \text{V}_{MAX}$	1	All		250	μА
current		V _C pin = 0.05 V,					
		T _A = +25°C					
Reference voltage	V _{REF}	Measured at FEEDBACK	1	All	1.224	1.264	V
		(FB) pin, V _C pin = 0.8 V	2,3	-	1.214	1.274	
Feedback input current	I _B	V _{FB} = V _{REF}	1	All		750	nA
			2,3	-		1100	_
Error amplifier transconductance	gm	$\Delta I_C = \pm 25 \mu A$	1	All	3000	6000	μmho
transconductance			2,3		2400	7000	
Error amplifier source or sink current		V _C pin = 1.5 V	1	All	150	350	μА
or sink current			2,3	-	120	400	
Reference voltage line regulation		$3 \text{ V} \leq \text{V}_{IN} \leq \text{V}_{MAX}$	1,2,3	All		0.03	%/V
regulation		V _C pin = 0.8 V					
Minimum input voltage			1,2,3	All		3.0	V
Control pin threshold		Duty cycle = 0	1	All	0.8	1.08	V
			2,3		0.6	1.25	
Output switch breakdown voltage	BV	$3 V \le V_{IN} \le V_{MAX}$	1,2,3	01,02, 03	65		V
		I _{SW} = 1.5 mA		04,05, 06	75		
Output switch "On" resistance	VSAT	I _{SW} = 4 A <u>3</u> /	1,2,3	01,04		0.24	Ω
		I _{SW} = 2 A <u>3</u> /	1	02,05		0.5	
		I _{SW} = 1 A <u>3</u> /	=	03,06		1.0	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

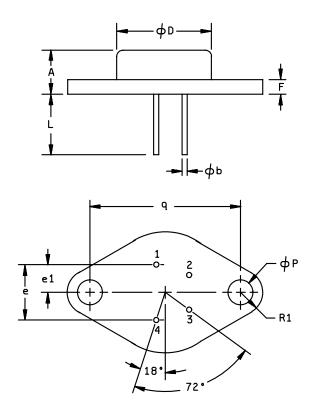
Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Switch current limit	I _{LIM}	Duty cycle = 50 %	1,2,3	01,04	5	11	А
		Duty cycle = 80 %			4	10	-
		Duty cycle = 50 %	-	02,05	2.5	5.5	-
		Duty cycle = 80 %	-		2	5	-
		Duty cycle = 50 %		03,06	1.25	3.5	-
		Duty cycle = 80 %			1	2.5	
Shutdown mode threshold voltage		$3 \text{ V} \leq \text{V}_{IN} \leq \text{V}_{MAX}$	1	All	100	250	mV
			2,3		50	300	-
Switching frequency			4	All	35	45	kHz
			5,6	•	33	47	1

- $\underline{1}$ / Unless otherwise specified, $V_{IN} = 15 \text{ V}$, V_{C} pin = 0.5 V, output pin open, and $V_{FB} = V_{REF}$. For device types 01, 02, and 03, $V_{MAX} = 40 \text{ V}$. For device types 04, 05, and 06, $V_{MAX} = 60 \text{ V}$.
- $2/V_{MAX}$ = 55 V for device types 04, 05, and 06 to avoid switch breakdown.
- 3/ Measured with V_C pin in high clamp, V_{FB} = 0.8 V.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 52 (see MIL-PRF-38535, appendix A).

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Case Y



Symbol	Inches		Millim	neters
	Min	Max	Min	Max
Α	.320	.350	8.128	8.890
φb	.038	.043	0.965	1.092
φD	.760	.775	19.30	19.69
е	.445	.465	11.30	11.81
e1	.220	.235	5.588	5.969
F	.060	.135	1.52	3.43
L	.420	.480	10.67	12.19
φP	.151	.161	3.84	4.09
q	1.177	1.197	29.90	30.40
R1	.167	.177	4.241	4.495

NOTE:

The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

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Device types	03	01, 02, 03,
,,		04, 05, 06
Case outlines	Р	Y
Terminal	Termina	l symbol
number		Š
1	GND	Vsw
		V 5 V V
2	Vc	Vc
	VC	vC
3	FEEDBACK (FB)	FEEDBACK (FB)
	, ,	, ,
4	NC	V _{IN}
		VIIN
5	V _{IN}	
	V IIV	
6	E1	
7	Vsw	
	V 3VV	
8	E2	

NOTES:

NC = No connection For case outline Y, case is ground

FIGURE 2. <u>Terminal connections</u>.

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4. QUALITY ASSURANCE PROVISIONS

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.
 - 4.2.1 Additional criteria for device class M.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition C. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.
 - 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
 - 4.4.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)			
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1</u> /	1,2,3,4,5,6 <u>1</u> /	1,2,3,4,5,6 <u>1</u> /
Group A test requirements (see 4.4)	1,2,3,4,5,6	1,2,3,4,5,6	1,2,3,4,5,6
Group C end-point electrical parameters (see 4.4)	1	1	1
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	1,4	1,4	1,4

- 1/ PDA applies to subgroup 1.
- 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition C. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - b. $T_A = +125^{\circ}C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

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- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the post irradiation end-point electrical parameter limits as defined in table I at TA = +25°C, after exposure, to the subgroups specified in table II herein.
 - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.
 - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43216-5000, or telephone (614) 692-0674.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
 - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	SIZE A		5962-90825
		REVISION LEVEL C	SHEET 12

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 00-08-29

Approved sources of supply for SMD 5962-90825 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-9082501MYA	64155	LT1070MK/883
5962-9082502MYA	64155	LT1071MK/883
5962-9082503MPA	64155	LT1072MJ8/883
5962-9082503MYA	64155	LT1072MK/883
5962-9082504MYA	64155	LT1070HVMK/883
5962-9082505MYA	64155	LT1071HVMK/883
5962-9082506MYA	64155	LT1072HVMK/883

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>Z</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

Vendor name and address

64155

Linear Technology Corporation 720 Sycamore Drive Milpitas, CA 95035-7487

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.